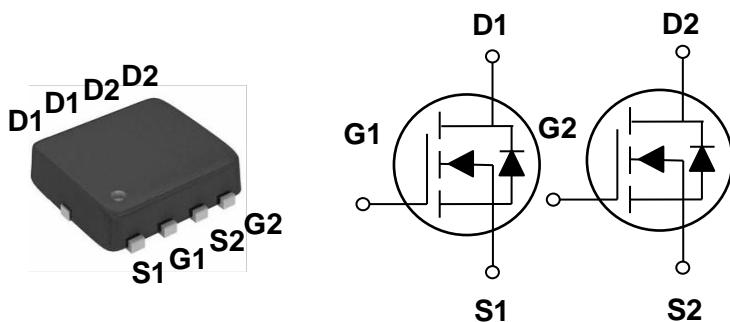


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK3X3 Dual Pin Configuration



BVDSS	RDS(ON)	ID
100V	200mΩ	7.8A

### Features

- 100V, 7.8A, RDS(ON) = 200mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load switch
- LED applications



### Absolute Maximum Ratings T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>Gs</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	7.8	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	4.9	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	31.2	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	27.1	W
	Power Dissipation – Derate above 25°C	0.21	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	4.6	°C/W



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100V Dual N-Channel MOSFETs

**SPC0810V**

### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

#### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	---	0.10	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

#### On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=4\text{A}$	---	160	200	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=2\text{A}$	---	170	210	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=1\text{A}$	---	5	---	S

#### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=2\text{A}$	---	13.4	21	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	2.9	6	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	1.7	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=3.3\Omega$	---	1.6	3	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	6.6	13	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	11.5	22	
$T_f$	Fall Time <sup>2, 3</sup>		---	3.6	7	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	820	1190	pF
$C_{\text{oss}}$	Output Capacitance		---	35	55	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	20	30	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.3	2.6	$\Omega$

#### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	7.8	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2</sup>		---	---	15.6	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

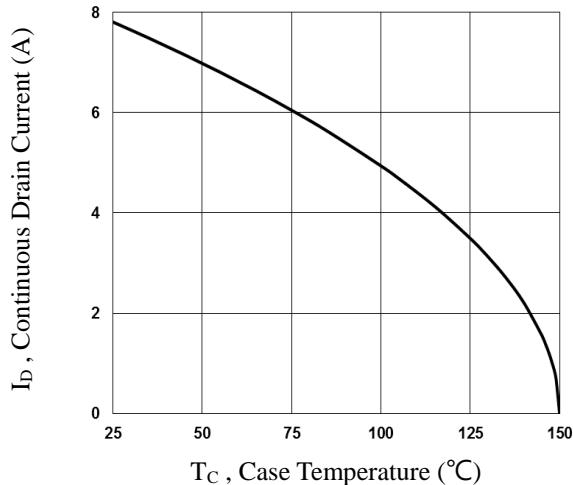
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.



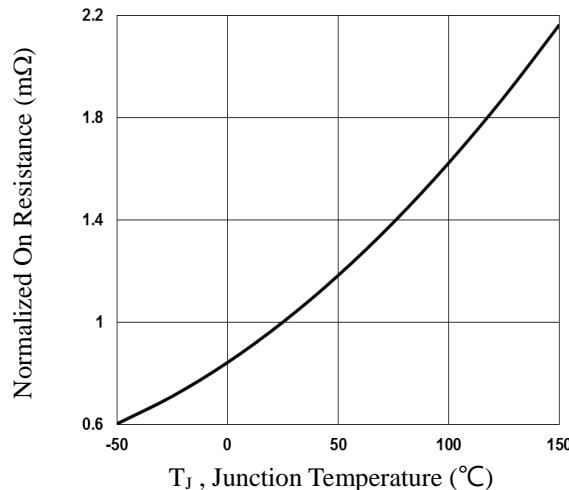
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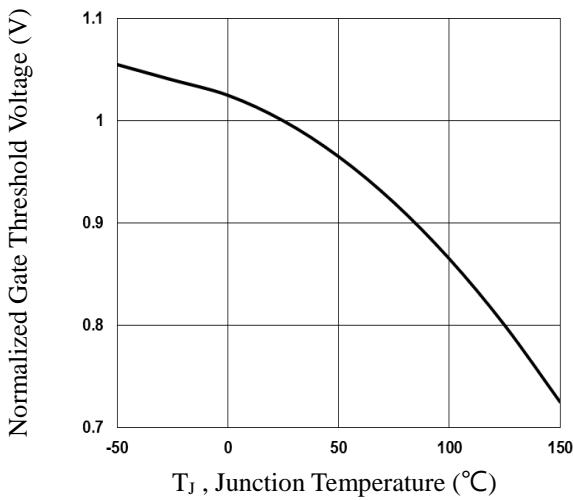
**SPC0810V**



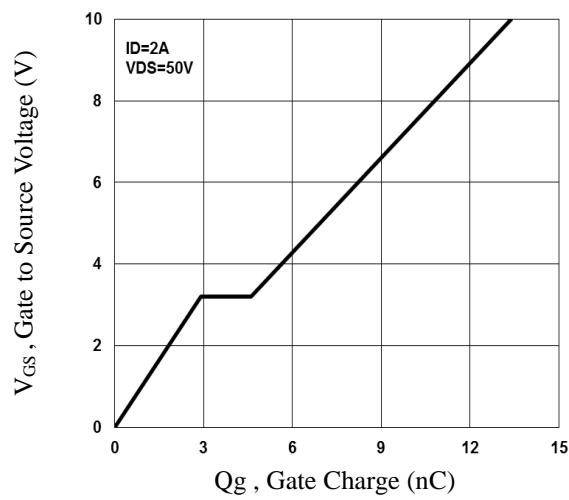
**Fig.1 Continuous Drain Current vs.  $T_C$**



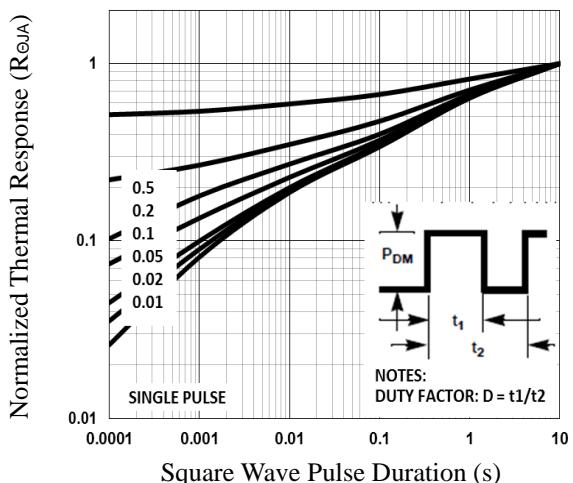
**Fig.2 Normalized  $R_{DS(ON)}$  vs.  $T_J$**



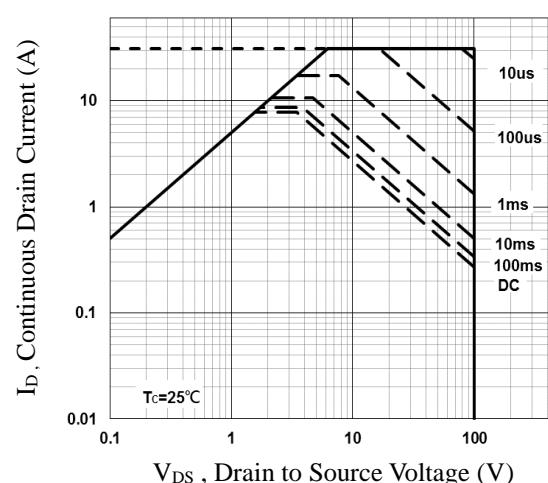
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



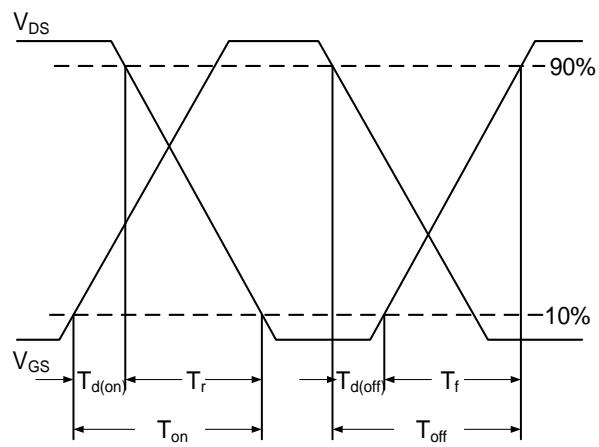
**Fig.4 Gate Charge Waveform**



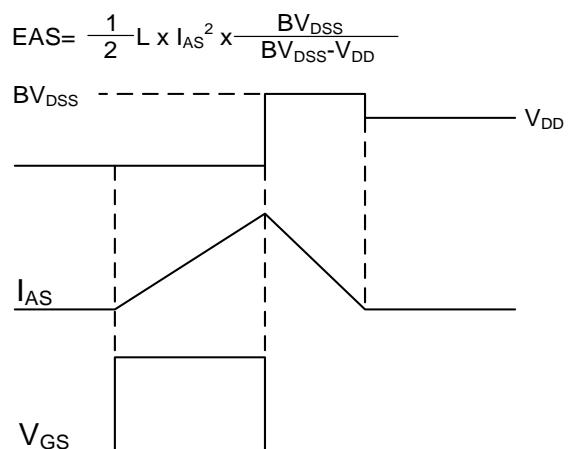
**Fig.5 Normalized Transient Response**



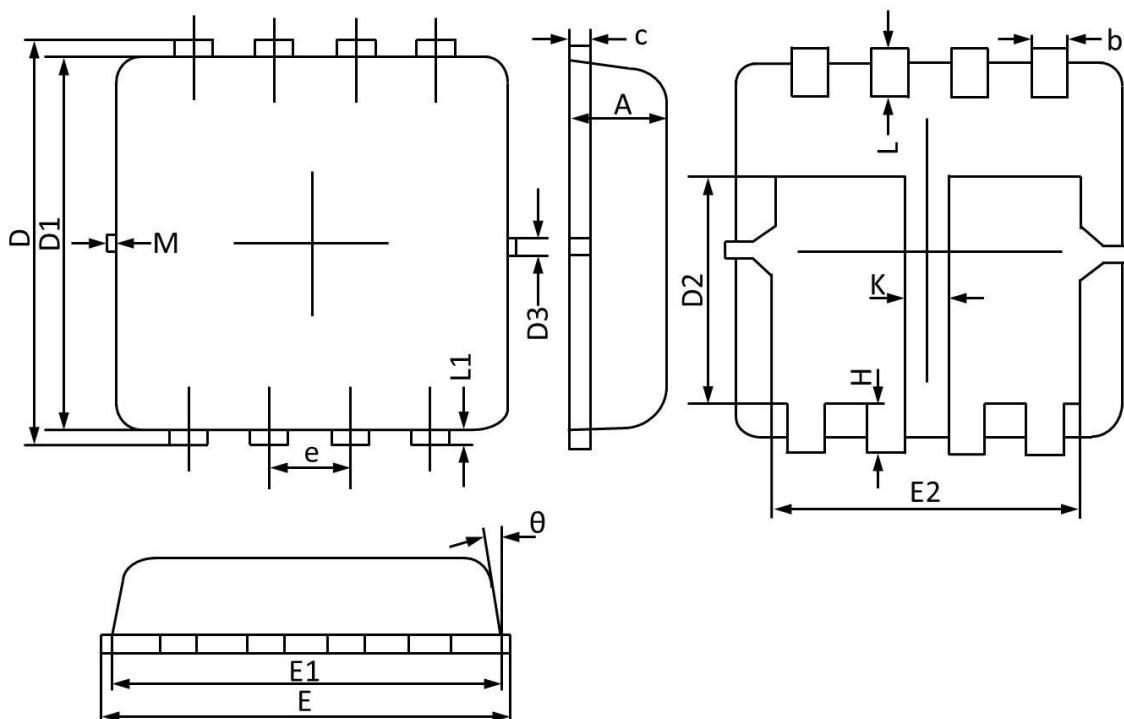
**Fig.6 Maximum Safe Operation Area**



**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

**PPAK3X3 Dual PACKAGE INFORMATION**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
K	0.300 REF		0.012 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	